

Ordering Information

Part Number	Package Option	Packing
TC8220K6-G	12-Lead DFN (4x4)	3000/Reel

-G denotes a lead (Pb)-free / RoHS compliant package

Product Summary

BV_{DSS}/BV_{DGS}		$R_{DS(ON)} (max)$	
N-Channel	P-Channel	N-Channel	P-Channel
200V	-200V	5.3Ω	6.5Ω

Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV_{DSS}
Drain-to-gate voltage	BV_{DGS}
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

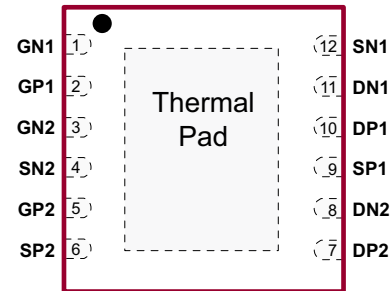
Typical Thermal Resistance

Package	θ_{ja}
12-Lead DFN	42°C/W

Note:

1.0oz, 4-layer, 3"x4" PCB.

Pin Configuration



12-Lead DFN
(top view)

Package Marking



Y = Last Digit of Year Sealed
W = Code for Week Sealed
L = Lot Number
— = "Green" Packaging

Package may or may not include the following marks: Si or

12-Lead DFN

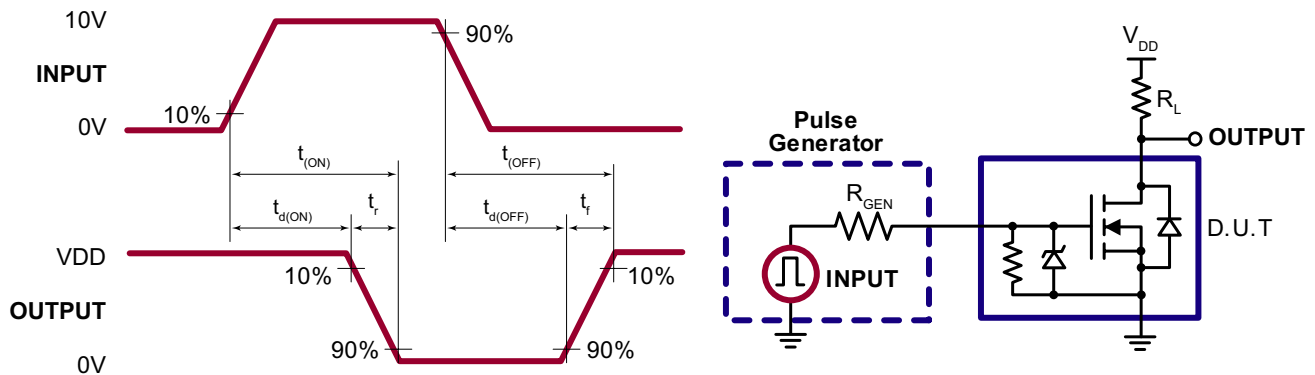
N-Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	200	-	-	V	$V_{GS} = 0V, I_D = 2.0mA$
$V_{GS(th)}$	Gate threshold voltage	1.0	-	2.4	V	$V_{GS} = V_{DS}, I_D = 1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-4.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = 1.0mA$
R_{GS}	Gate-to-source shunt resistor	10	-	50	K Ω	$I_{GS} = 100\mu A$
VZ_{GS}	Gate-to-source Zener voltage	13.2	-	25	V	$I_{GS} = 2.0mA$
I_{DSS}	Zero gate voltage drain current	-	-	10.0	μA	$V_{DS} = \text{Max rating}, V_{GS} = 0V$
		-	-	1.0	mA	$V_{DS} = 0.8 \text{ Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	On-state drain current	1.3	-	-	A	$V_{GS} = 5.0V, V_{DS} = 25V$
		2.3	-	-		$V_{GS} = 10V, V_{DS} = 50V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	-	6.5	Ω	$V_{GS} = 5.0V, I_D = 150mA$
		-	-	6.0		$V_{GS} = 10V, I_D = 1.0A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.0	%/ $^\circ\text{C}$	$V_{GS} = 10V, I_D = 1.0A$
G_{FS}	Forward transconductance	400	-	-	mmho	$V_{DS} = 25V, I_D = 500mA$
C_{ISS}	Input capacitance	-	56	-	pF	$V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	13	-		
C_{RSS}	Reverse transfer capacitance	-	2.0	-		
$t_{d(ON)}$	Turn-on delay time	-	-	10	ns	$V_{DD} = 25V,$ $I_D = 1.0A,$ $R_{GEN} = 25\Omega$
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-off delay time	-	-	20		
t_f	Fall time	-	-	15		
V_{SD}	Diode forward voltage drop	-	-	1.8	V	$V_{GS} = 0V, I_{SD} = 500mA$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = 500mA$

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

N-Channel Switching Waveforms and Test Circuit



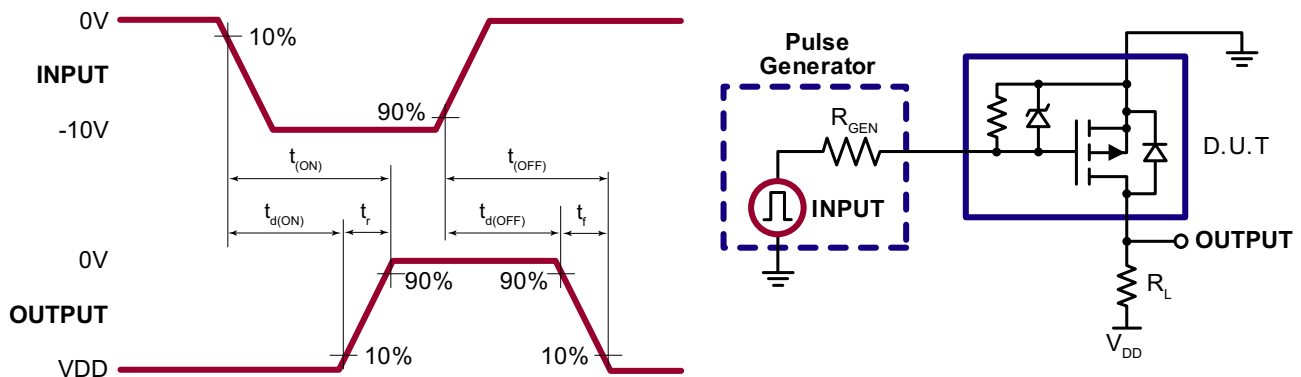
P-Channel Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	-200	-	-	V	$V_{GS} = 0V, I_D = -2.0mA$
$V_{GS(th)}$	Gate threshold voltage	-1.0	-	-2.4	V	$V_{GS} = V_{DS}, I_D = -1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	4.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = -1.0mA$
R_{GS}	Gate-to-source shunt resistor	10	-	50	K Ω	$I_{GS} = 100\mu A$
VZ_{GS}	Gate-to-source Zener voltage	13.2	-	25	V	$I_{GS} = -2.0mA$
I_{DSS}	Zero gate voltage drain current	-	-	-10	μA	$V_{DS} = \text{Max rating}, V_{GS} = 0V$
		-	-	-1.0	mA	$V_{DS} = 0.8 \text{ Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	On-state drain current	-1.2	-	-	A	$V_{GS} = -5.0V, V_{DS} = -25V$
		-2.3	-	-		$V_{GS} = -10V, V_{DS} = -50V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	-	8.5	Ω	$V_{GS} = -5.0V, I_D = -150mA$
		-	-	7.0		$V_{GS} = -10V, I_D = -1.0A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.0	%/ $^\circ\text{C}$	$V_{GS} = -10V, I_D = -1.0A$
G_{FS}	Forward transconductance	400	-	-	mmho	$V_{DS} = -25V, I_D = -500mA$
C_{ISS}	Input capacitance	-	75	-	pF	$V_{GS} = 0V, V_{DS} = -25V, f = 1.0MHz$
C_{OSS}	Common source output capacitance	-	21	-		
C_{RSS}	Reverse transfer capacitance	-	6.5	-		
$t_{d(ON)}$	Turn-on delay time	-	-	10	ns	$V_{DD} = -25V, I_D = -1.0A, R_{GEN} = 25\Omega$
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-off delay time	-	-	20		
t_f	Fall time	-	-	15		
V_{SD}	Diode forward voltage drop	-	-	-1.8	V	$V_{GS} = 0V, I_{SD} = -500mA$
t_{rr}	Reverse recovery time	-	300	-	ns	$V_{GS} = 0V, I_{SD} = -500mA$

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300 μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

P-Channel Switching Waveforms and Test Circuit



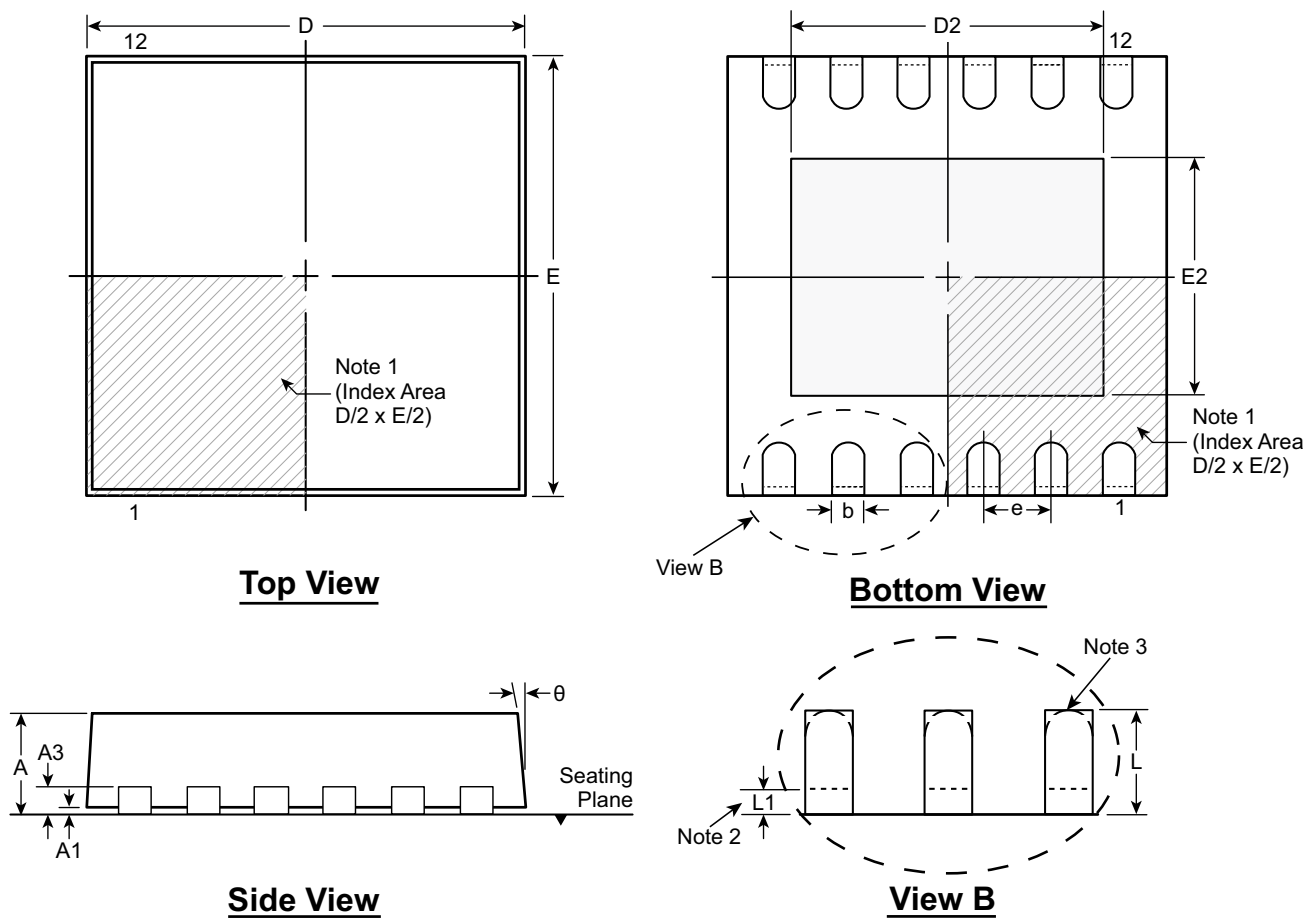
Pin Description

Pin #	Function	Description	Pin #	Function	Description
1	GN1	Gate of N-MOSFET 1	7	DP2	Drain of P-MOSFET 2
2	GP1	Gate of P-MOSFET 1	8	DN2	Drain of N-MOSFET 2
3	GN2	Gate of N-MOSFET 2	9	SP1	Source of P-MOSFET 1
4	SN2	Source of N-MOSFET 2	10	DP1	Drain of P-MOSFET 1
5	GP2	Gate of P-MOSFET 2	11	DN1	Drain of N-MOSFET 1
6	SP2	Source of P-MOSFET 2	12	SN1	Source of N-MOSFET 1
Thermal Pad		Die attachment substrate, must be grounded externally			

Note:

Thermal Pad must be grounded.

12-Lead DFN Package Outline (K6)
4.00x4.00mm body, 1.00mm height (max), 0.50mm pitch



- Notes:**
- 1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
 - 2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
 - 3. The inner tip of the lead may be either rounded or square.

Symbol		A	A1	A3	b	D	D2	E	E2	e	L	L1	θ
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	3.85	3.19	3.85	2.29	0.50 BSC	0.30	0.00	0°
	NOM	0.90	0.02		0.25	4.00	3.34	4.00	2.44		0.40	-	-
	MAX	1.00	0.05		0.30	4.15	3.44	4.15	2.54		0.50	0.15	14°

Drawings not to scale.
Supertex Doc.#: DSPD-12DFNK64X4P050, Version A030210.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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